

Fig. 1

PRIOR ART

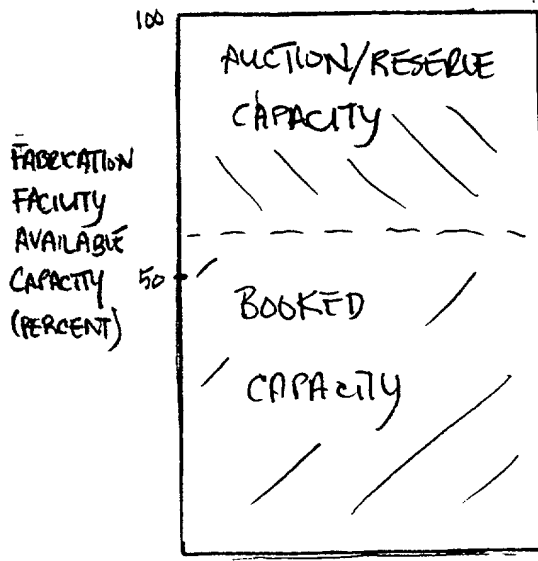


Fig. 2

AUCTION PARAMETERS

QUANTITY : 1 UNIT OF 300 WAFERS

TECHNOLOGY : 0.15 MICRON LOGIC

PROCESSING : 2 POLYSILICON LAYERS
2 METAL LAYERS
SHALLOW TRENCH ISOLATION

DELIVERY : 2 MONTHS AFTER WAFER RELEASE

Fig. 3

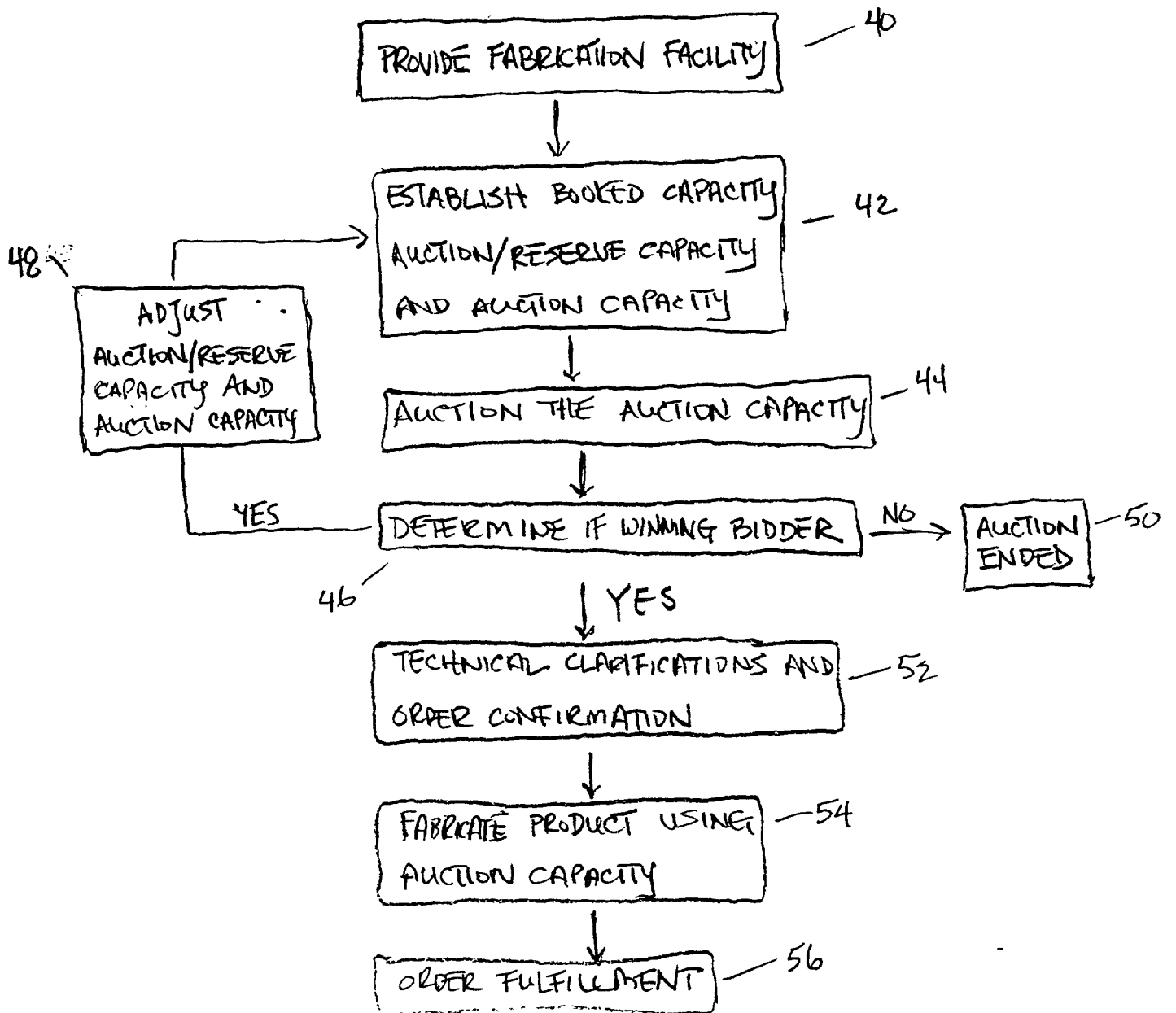


Fig. 4